



General Description

It combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$. It is suitable for automotive application.

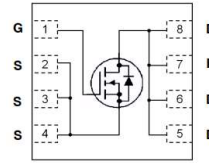
Features

- AEC-Q101 Qualified
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

Application

- BLDC Motor driver
- DC-DC
- Battery protection

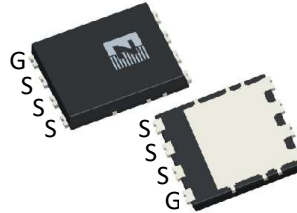
Product Summary



$$V_{DS} = 60V$$

$$R_{DS(ON)} = 1.2m\Omega$$

$$I_D = 292A$$



DFN8*8



Ordering Information:

Part NO.	ZMSA012N06HG
Marking	ZMS012N06H
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

Absolute Maximum Ratings ($T_C=25^\circ C$)

Parameter	Symbol	Conditions	Value	Unit
Drain-Source Voltage	V_{DS}		60	V
Gate-Source Voltage ^①	V_{GS}		± 20	V
Continuous Drain Current	I_D	$T_C=25^\circ C$	292	A
	I_D	$T_C=75^\circ C$	231	A
	I_D	$T_C=100^\circ C$	200	A
Pulsed Drain Current	I_{DM}	Pulsed; $t_p \leq 10 \mu s$; $T_{mb} = 25^\circ C$	876	A
Total Power Dissipation	P_D	$T_C=25^\circ C$	231	W
Total Power Dissipation	P_D	$T_A=25^\circ C$	4.3	W
Operating Junction Temperature	T_J		-55 to +175	$^\circ C$
Storage Temperature	T_{STG}		-55 to +175	$^\circ C$
Single Pulse Avalanche Energy	E_{AS}	$L=0.1mH$, $V_{GS}=10V$, $R_g=25\Omega$	320	mJ
		$L=0.5mH$, $V_{GS}=10V$, $R_g=25\Omega$	460	mJ
ESD Level (HBM)	CLASS 2			



•Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}		-	0.65	°C/W
Thermal resistance, junction-ambient	$R_{thJA}^{(2)}$		-	35	°C/W
Soldering temperature (total time<10s)	Tsold		-	260	°C

•Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	60			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	2.0	2.7	4.0	V
Drain-Source Leakage Current	I_{DSS}	$V_{GS}=0V, V_{DS}=60V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=40A$		1.2	1.6	m Ω
Forward Transconductance	g_{FS}	$V_{DS}=5V, I_{SD}=10A$		15		S
Diode Forward Voltage	V_{FSD}	$V_{GS}=0V, I_{SD}=40A$			1.3	V

•Dynamic characteristics

Parameter	Symbol	Condition	Min.	Typ.	Max.	Unit
Input capacitance	C_{iss}	$f=1MHz, V_{DS}=25V$	-	4950	-	pF
Output capacitance	C_{oss}		-	1800	-	
Reverse transfer capacitance	C_{rss}		-	72	-	
Gate Resistance	R_g	$f=1MHz$	-	1.6	-	Ω
Total gate charge	Q_g	$V_{DD}=15V,$ $I_D=40A,$ $V_{GS}=10V$	-	67	-	nC
Gate - Source charge	Q_{gs}		-	17	-	
Gate - Drain charge	Q_{gd}		-	14	-	
Turn-ON Delay time	$t_{D(on)}$	$V_{GS}=10V, V_{DS}=15V,$ $R_G=3.3\Omega, I_D=20A$	-	15	-	ns
Turn-ON Rise time	t_r		-	10	-	ns
Turn-Off Delay time	$t_{D(off)}$		-	26	-	ns
Turn-Off Fall time	t_f		-	17	-	ns
Reverse Recovery Time	t_{RR}	$V_{DD}=20V, dI_S/dt=$ $100A/\mu s, I_S=50A$	-	48	-	ns
Reverse Recovery Charge	Q_{RR}		-	47	-	nC



Fig.1 Gate-Charge Characteristics

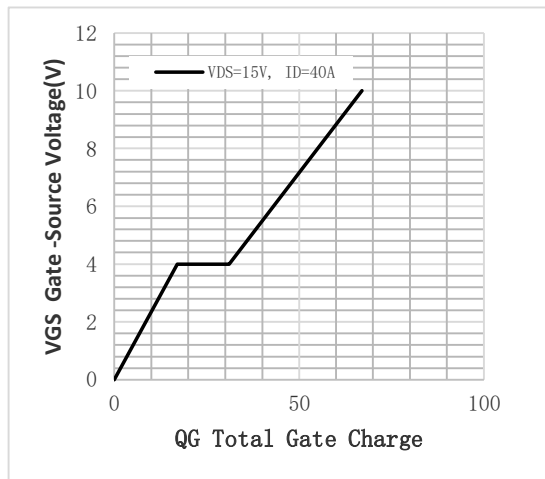


Fig.2 Capacitance Characteristics

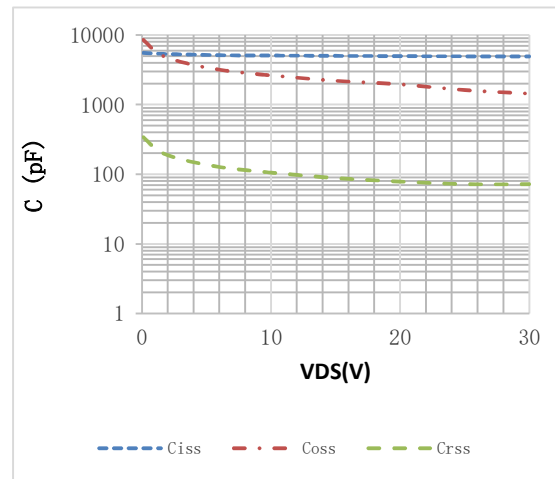


Fig.3 Power Dissipation

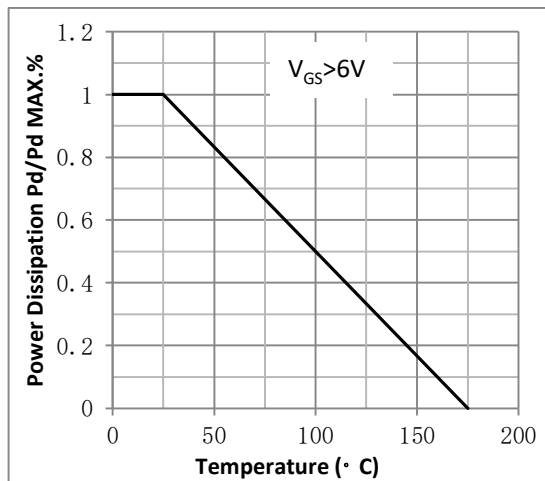


Fig.4 Typical output Characteristics

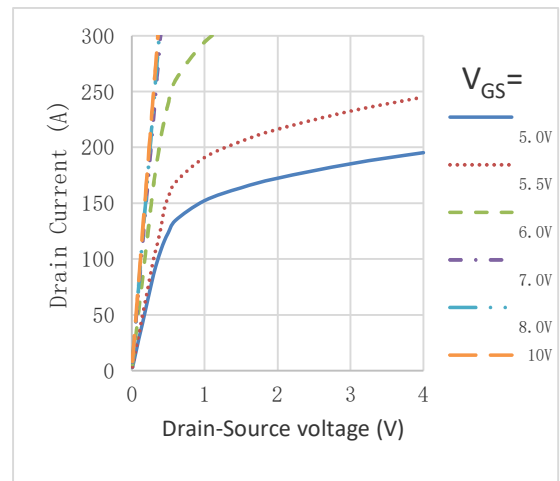


Fig.5 Threshold Voltage V.S Junction Temperature

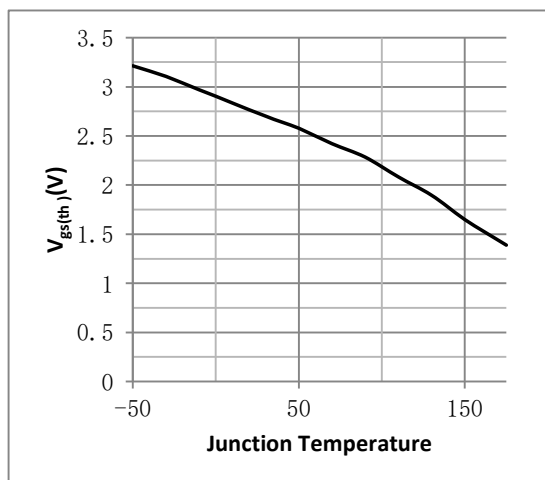


Fig.6 Resistance V.S Drain Current

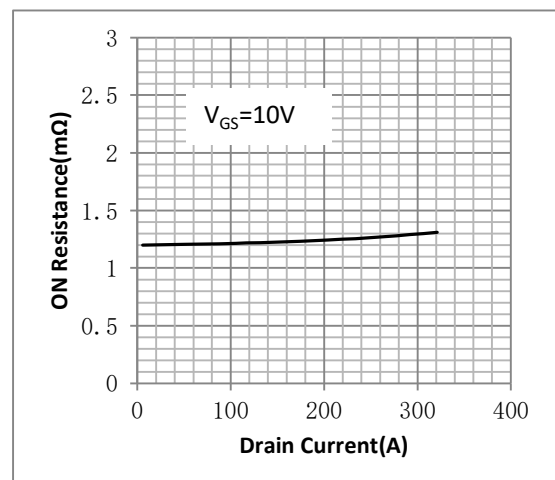


Fig.7 On-Resistance VS Gate Source Voltage

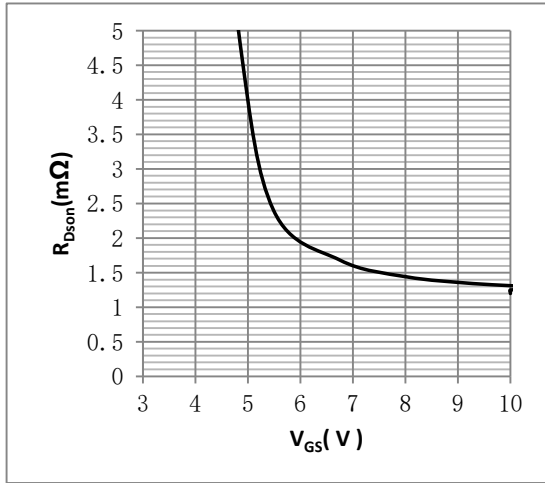


Fig.8 On-Resistance V.S Junction Temperature

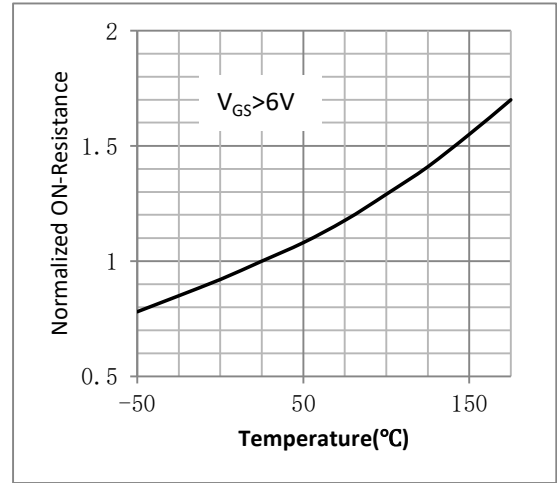


Figure 9. Diode Forward Voltage vs. Current

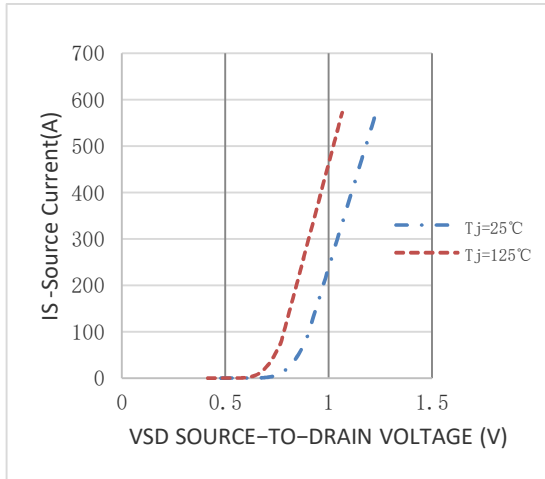


Figure 10. Transfer Characteristics

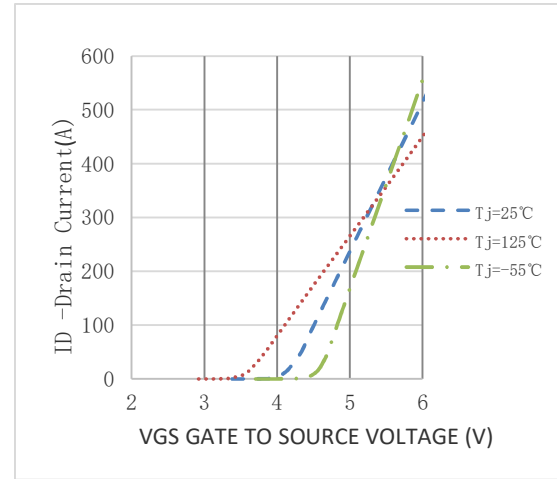
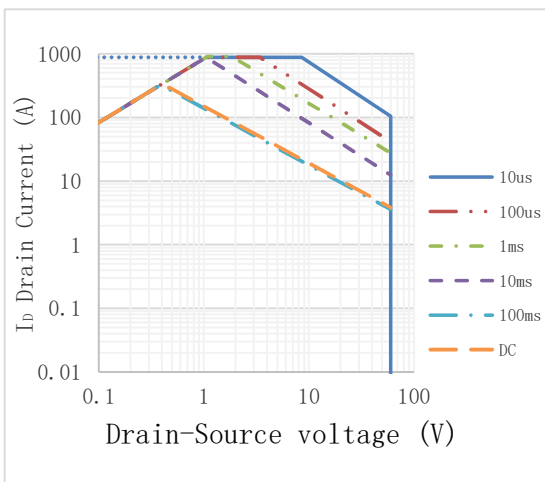
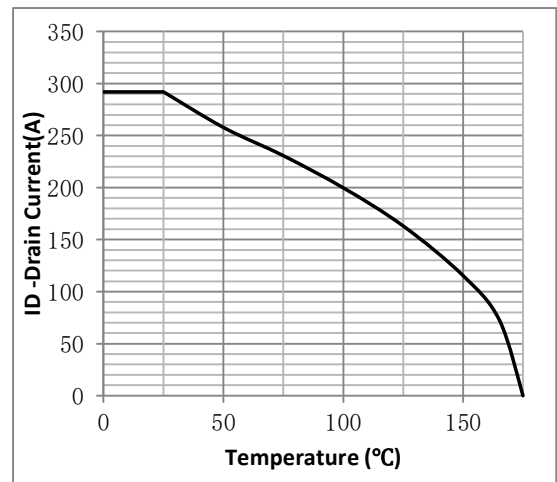
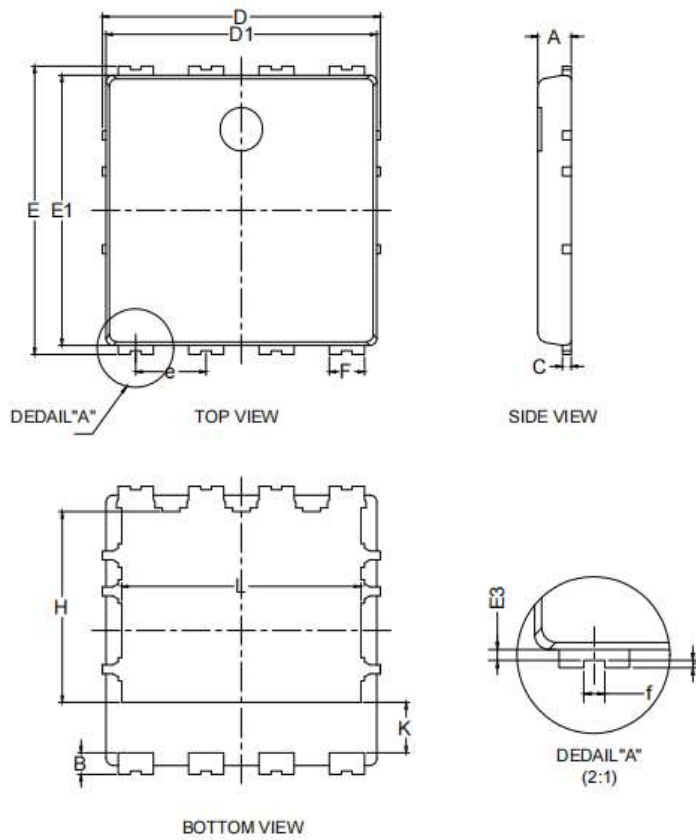


Fig.11 Safe Operating Area


Fig.12 ID vs. Junction Temperature^③




•DFN8*8 Package Outline



MILLIMETERS			
DIM	MIN	TYP	MAX
A	0.90	0.95	1.00
B	0.50	0.60	0.70
C	0.254TYP		
D	7.80	7.90	8.00
D1	7.60	7.70	7.80
E	7.90	8.00	8.10
E1	7.40	7.50	7.60
e	2.00TYP		
F	1.00TYP		
H	5.15	5.30	5.40
L	6.60	6.80	6.90
K	1.20	—	—
E2	0.04	0.10	0.16
E3	0.10	0.15	0.20
f	0.25	0.30	0.35

**Note:**

- ① Pulse : $V_{GS}=+20V/-20V$, Duty cycle=50%, $T_j=175^{\circ}C$, $t=1000$ hours; For DC , the following test conditions can be passed: $V_{GS}=+20V/-10V$, $T_j=175^{\circ}C$, $t=1000$ hours ;
- ② Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate;
- ③ Practically the current will be limited by PCB, thermal design and operating temperature. $V_{GS}=10V$.

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Revision History

Version	Date	Change
A	2024/8/15	New